

The 30th IEEE Asian Test Symposium (ATS 2021)

November 22–25, 2021—Virtual Event Hosted by Japan—

**The organizing committee has decided to hold this symposium virtually due to the COVID-19 pandemic.*

ATS

Call for Papers

The Asian Test Symposium (ATS) provides an open forum for researchers and industrial practitioners from all countries of the world to exchange innovative ideas on system, board, and device testing with design, manufacturing, and field consideration in mind.

Scope

Topics of interest include (but are not limited to):

- Analog/Mixed-Signal Test
- Automatic Test Generation
- Board Test and Diagnosis
- Boundary Scan Test
- Built-In Self-Test (BIST)
- Connectivity Testing
- Defect-Based Test
- Delay and Performance Test
- Dependability and Functional Safety
- Design for Test (DFT)
- Diagnosis and Silicon Debug
- Economic of Test
- Failure Analysis
- Fault Modeling and Simulation
- Fault Tolerance
- GPU Test
- Hardware-Oriented Security and trust
- High-Speed I/O Test
- Low-Power IC Test
- Machine Learning in Test
- Memory Test and Repair
- Multi-/Many-core Processor Test
- Online Test
- Power/Thermal/Reliability Issues in Test
- Reconfigurable System Test
- RF Test
- Self-Repair
- SiP, Stacked, 3D IC Test
- Standards in Test
- Test Compression
- Test for Biomedical Circuits and Systems
- Test for MEMS and Microfluidic Systems
- Test for Nanoscale Devices and Emerging Technologies
- Test for Reversible and Quantum Circuits
- Test for Sensors and IoT
- Test Quality
- Test Synthesis
- Validation and Verification
- Yield Analysis and Enhancement

Regular Session

The ATS 2021 Organizing Committee invites original, unpublished paper submissions on the above topics. Paper submission shall be complete manuscripts, not exceeding six pages in a standard IEEE two-column format. The submission will be considered evidence that upon acceptance the author(s) will submit a final camera-ready version of the paper for inclusion in the proceedings, and will present the paper at the symposium. Each accepted contribution must have at least one full paid registration by the time the camera ready paper is submitted for inclusion in the proceedings. ATS reserves the right to remove from IEEE Xplore papers not presented at the symposium.

Industry Session

This session will address a wide range of practical problems in LSI test, board and system test, diagnosis, failure analysis, design verification, and so on. A one-page abstract is required for submission. Each submission should also include the complete address and designate a contact person and a presenter. Abstract submissions should be emailed to Industry Chair (e-mail: ats2021ic@aries30.cse.kyutech.ac.jp)

Key Dates

Submission deadline:	June 19, 2021	June 23, 2021
Notification of acceptance:	August 6, 2021	August 6, 2021
Camera ready manuscript:	September 7, 2021	September 7, 2021

Sponsors



General Co-Chair:

Yukiya Miura
(Tokyo Metropolitan University, Japan)

Satoshi Ohtake
(Oita University, Japan)

General-Vice Chair:

Hideyuki Ichihara
(Hiroshima City University, Japan)

Program Chair:

Yoshinobu Higami
(Ehime University, Japan)

Program-Vice Chair:

Hiroyuki Yotsuyanagi
(Tokushima University, Japan)

Finance Chair:

Masayuki Arai
(Nihon University, Japan)

Local Arrangement Chair:

Senling Wang
(Ehime University, Japan)

Registration Chair:

Satoshi Komatsu
(Tokyo Denki University, Japan)

Registration-Vice Chair:

Hiroshi Yokoyama
(Akita University, Japan)

Publicity Chair:

Tsuyoshi Iwagaki
(Hiroshima City University, Japan)

Publication Chair:

Stefan Holst
(Kyushu Institute of Technology, Japan)

Industry Chair:

Masahiro Ishida
(Advantest Corp., Japan)

Tutorial Chair:

Michihiro Shintani
(NAIST, Japan)

Secretary:

Kohei Miyase
(Kyushu Institute of Technology, Japan)

North American Liaison:

Krishnendu Chakrabarty
(Duke University)

European Liaison:

Erik Larsson (Lund University)



<https://www.ats2021.info/hiroshima-cu.ac.jp/>
<https://www.ats2021.info/hiroshima-cu.ac.jp/>